

# BA891

**Band-switching diode**

**Rev. 04 — 8 January 2008**

**Product data sheet**

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NXP Semiconductors

# Band-switching diode

**BA891**

## FEATURES

- Ultra small plastic SMD package
- Low diode capacitance: max. 1.05 pF
- Low diode forward resistance: max. 0.7  $\Omega$
- Small inductance.

## APPLICATIONS

- Low loss band-switching in VHF television tuners
- Surface mount band-switching circuits.

## DESCRIPTION

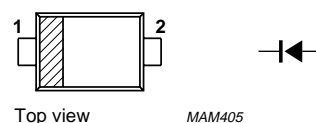
The BA891 is a planar high performance band-switching diode in the ultra small SOD523 SMD plastic package.

## MARKING

| TYPE NUMBER | MARKING CODE |
|-------------|--------------|
| BA891       | 7            |

## PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | cathode     |
| 2   | anode       |



The marking band indicates the cathode.

Fig.1 Simplified outline (SOD523) and symbol.

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL    | PARAMETER                  | CONDITIONS                         | MIN. | MAX. | UNIT               |
|-----------|----------------------------|------------------------------------|------|------|--------------------|
| $V_R$     | continuous reverse voltage |                                    | –    | 35   | V                  |
| $I_F$     | continuous forward current |                                    | –    | 100  | mA                 |
| $P_{tot}$ | total power dissipation    | $T_s = 90\text{ }^{\circ}\text{C}$ | –    | 715  | mW                 |
| $T_{stg}$ | storage temperature        |                                    | –65  | +150 | $^{\circ}\text{C}$ |
| $T_j$     | junction temperature       |                                    | –65  | +150 | $^{\circ}\text{C}$ |

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THERMAL CHARACTERISTICS

| SYMBOL        | PARAMETER   | VALUE | UNIT |
|---------------|---|-------|------|
| $R_{th\ j-s}$ | thermal resistance from junction to soldering point | 85    | K/W  |

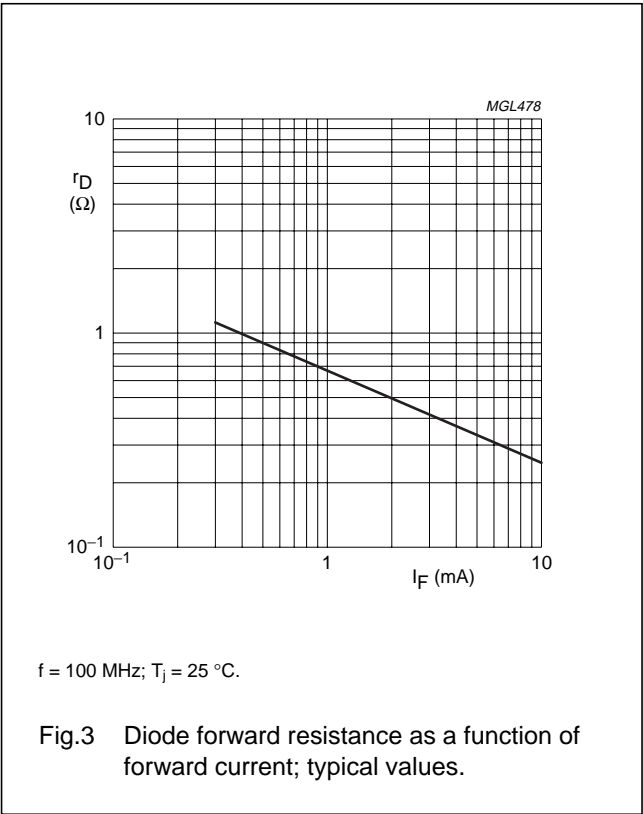
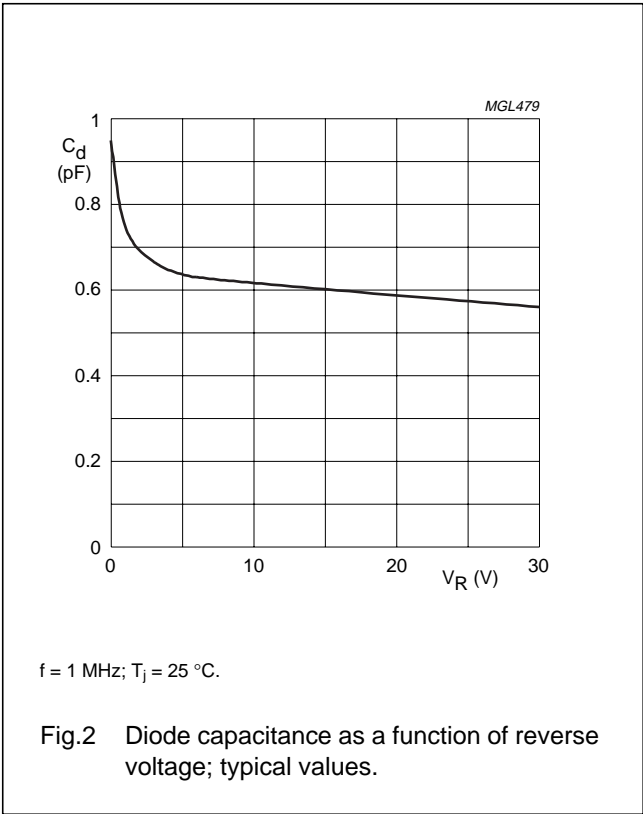
CHARACTERISTICS

$T_j = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

| SYMBOL | PARAMETER                | CONDITIONS  | TYP.         | MAX.        | UNIT                 |
|--------|--------------------------|---|--------------|-------------|----------------------|
| $V_F$  | forward voltage          | $I_F = 10\text{ mA}$  | –            | 1           | V                    |
| $I_R$  | reverse current          | $V_R = 30\text{ V}$   | –            | 20          | nA                   |
| $C_d$  | diode capacitance        | $f = 1\text{ MHz}$ ; note 1; see Fig.2<br>$V_R = 1\text{ V}$<br>$V_R = 3\text{ V}$      | 0.8<br>0.65  | 1.05<br>0.9 | pF<br>pF             |
| $r_D$  | diode forward resistance | $f = 100\text{ MHz}$ ; note 1; see Fig.3<br>$I_F = 3\text{ mA}$<br>$I_F = 10\text{ mA}$ | 0.42<br>0.28 | 0.7<br>0.5  | $\Omega$<br>$\Omega$ |
| $L_S$  | series inductance        |   | 0.6          | –           | nH                   |

Note

1. Guaranteed on AQL basis; inspection level S4, AQL 1.0.



Band-switching diode

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PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD523

0 0.5 1 mm  
scale

**DIMENSIONS (mm are the original dimensions)**

| UNIT | A            | b <sub>p</sub> | c            | D            | E            | H <sub>E</sub> | v   |
|------|--------------|----------------|--------------|--------------|--------------|----------------|-----|
| mm   | 0.65<br>0.58 | 0.34<br>0.26   | 0.17<br>0.11 | 1.25<br>1.15 | 0.85<br>0.75 | 1.65<br>1.55   | 0.1 |

**Note**  
1. The marking bar indicates the cathode.

| OUTLINE<br>VERSION | REFERENCES |       |       |  | EUROPEAN<br>PROJECTION | ISSUE DATE             |
|--------------------|------------|-------|-------|--|------------------------|------------------------|
|                    | IEC        | JEDEC | JEITA |  |                        |                        |
| SOD523             |            |       | SC-79 |  |                        | -02-12-13-<br>06-03-16 |

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### Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## Revision history

### Revision history

| Document ID  | Release date | Data sheet status     | Change notice | Supersedes |
|--|--------------|-----------------------|---------------|------------|
| BA891_N_4  | 20080108     | Product data sheet    | -             | BA891_3    |
| Modifications: <ul style="list-style-type: none"><li>Package outline on page 4 changed</li></ul> |              |                       |               |            |
| BA891_3<br>(9397 750 09281)  | 20020125     | Product specification | -             | BA891_2    |
| BA891_2<br>(9397 750 04308)  | 19980831     | Product specification | -             | BA891_1    |
| BA891_1<br>(9397 750 04193)  | 19980818     | Product specification | -             | -          |

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